

WHAT IS CLAIMED IS:

1. A slurry feeding apparatus for feeding polishing slurry to a chemical/mechanical polisher, the apparatus comprising:

a container for storing the slurry therein;

a first nozzle for sucking the slurry up from the container;

a second nozzle for recovering the slurry back to the container;

a third nozzle for dripping the slurry in the polisher;

a first pipe, which is connected to the first and third nozzles for delivering the slurry to the polisher;

a second pipe, which is connected to the second nozzle and the first pipe for bypassing at least part of the slurry flowing through the first pipe from the third nozzle and then recovering that part of the slurry back to the second nozzle;

a control valve for regulating the flow rate of the slurry, which is now flowing through the first pipe and will be supplied to the third nozzle and the second pipe; and

a pump, which is provided for at least one of the first and second pipes for making the slurry flow with a pressure applied,

wherein the first nozzle sucks up portion of the slurry that is located higher than the bottom of the container by a predetermined distance or more.

2. The apparatus of claim 1, wherein the first nozzle sucks up portion of the slurry that is located higher than the bottom of the container by 5 centimeters or more.

3. The apparatus of claim 1, wherein the end of the first nozzle is cut away obliquely with respect to the axis thereof.

4. The apparatus of claim 1, wherein the end of the first nozzle is closed, and wherein the side of the first nozzle is provided with a plurality of openings for sucking the slurry up therethrough.

5. The apparatus of claim 1, further comprising a mechanism for adjusting the level of the first nozzle at the end thereof.

6. A method for feeding polishing slurry to a chemical/mechanical polisher,

wherein the slurry delivered from a container to the polisher is located higher than the bottom of the container by a predetermined distance or more.

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